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TABLE OF CONTENTS

SEMICONDUCTOR THERMAL MEASUREMENT, MODELING AND MANAGEMENT SYMPOSIUM

Welcome to SEMI-THERM 40	iii
Committees	v
Short Courses	vii
Keynote Speaker: Tim Shedd, Dell; Lunch Speakers: Ken Joyce, Sarah da Silva Andrade.....	xv
Panel Discussion: Artificial Intelligence and its Implication for Thermal Engineers	xvii
Thermi Award: Wendy Luiten, Philips	xxv
Rosten Award: Szilárd Zsigmond Szóke, Henrik Sebők	xxvi
Thermal Hall of Fame Award: Bonnie Crystall and Walter Schuch	xxvii

Session 1 - Consumer Electronics

Investigation on Pulsating Heat Pipe (PHP) Heat Spreader Plate for Electronics Cooling	1
Sai Kiran Hota, Kuan-Lin Lee, Greg Hoeschele, Srujan Rakkam, Advanced Cooling Technologies	
Cell Degradation and Energy Release During Battery Failures *	
Francesco Colella, Exponent Inc.	
Single- and Multi-Voltage IC Circuit Thermal Runaway Analysis and Application	7
Sam Zhao, Broadcom	

Session 2 - Data Center Cooling

Datacenter PUE Comparison: Direct Liquid Cooling vs. 2-Phase Immersion Cooling *	
Mark North, Nvidia	
Study on the Characterization of Filters for a Direct-to-chip Liquid Cooling System	13
Pardeep Shahi ¹ , Ali Heydari ¹ , Himanshu Modi ² , Lochan Sai Reddy Chinthaparthi ² , Anto Barigala ² , Qusai Soud ¹ , Uschas Chowdhury ¹ , Dereje Agonafer ² , Mohammad Tradat ¹ , Jeremy Rodriguez ¹ , ¹ Nvidia, ² University of Texas at Arlington	
Improved PIDNN for Server Fan Speed Control	19
Zheng Song, Wenbin Tian, Haifeng Gong, Nishi Ahuja, Intel Asia-Pacific Research & Development Ltd.	
Investigation of Flow Restrictors for Rack Level Two-Phase Cooling under Nonuniform Heating	26
Serdar Ozguc, Qingyang Wang, Akshith Narayanan, Richard W. Bonner III, Accelsius	

Session 3 - Testing and Measurement Methods

Investigation of Relaxation and Recovery Effects in Solid Thermal Interface Materials Under Operation Conditions *	
Antonio Harder, Berliner Nanotest und Design GmbH	
Thermal Test Vehicle for Investigation of Thermal Path in Large Die Area Packages by Thermal Transient Impedance Analysis *	
Mohamad Abo Ras, Berliner Nanotest und Design GmbH	
Development of a Controlled Warpage Thermal Test Vehicle *	
Shourya Jain, Laird Performance Materials, DuPont	
Thermal Characterization of Multi-Source Devices: Alternative Way to Determine the Thermal Characterization Matrix	32
Dirk Schweitzer, Marco Pennetti, Infineon Technologies AG	

Session 4 - CFD/Numerical Methods

Simulation of Solder Fatigue Effects on Typical BGA Package due to Material and Temperature Variations	36
James Petroski ¹ , Andy Carrasco ² , ¹ Design by Analysis Technical Consulting, ² Flexetch	
Accurate Thermal Design of Chiplelets in Heterogeneous Packaging by Embedding FANTASTIC BCI-ROMs in CFD Models *	
John Wilson, Siemens Digital Industries Software	
Evaluating the Thermal Performance of TPMS Structures: A Comparative Study between Pins, Fins and Gyroids in Electronics Cooling *	
Lieven Vervecken, Diabatix	
Modeling the Impact of Thermal Management on Electric Vehicle Energy Consumption and Driving Range **	46
Timofey Golubev, Logan Canull, and Zachary Edel, ThermoAnalytics Inc.	

Session 5 - Thermal Interface Materials

Graphene Enhanced Thermal Interface Materials for Electronics Cooling Applications *	
Johan Liu, SHT Smart High Tech AB	
Liquid Metal Embedded Elastomers (LMEE) as Low-BLT Thermal Interface Materials **	53
Keyton Feller, Dylan Shah, Loran Russel, Navid Kazem, Arieca	
Innovative Metal TIM Technology for TIM1 in BGA Style Semiconductor Packages *	
Timothy Jensen, Indium Corporation	
Integration of Thermally Conductive Tacky Agents with Compressible Thermal Interface Materials (TIMs) to Improve Thermal Performance *	
Miloš Lazić, Indium Corporation	
Advanced Heat Removal, An Electronics Overmolding Advantage	57
Troy Diaz, X2F	

Session 6 - Emerging Technologies

Aluminum Boiling-driven Heat Spreader for High Heat Dissipation *	
Jungho Lee, Ajou University	
Thermal Management of Wide-Bandgap Semiconductor Amplifiers used for Plasma Heating and Control **	62
Sangeeta P. Vinoth ¹ , Xuhui Feng ² , Christopher Galea ¹ , Gilbert Moreno ² , Michael Paluszek ¹ , Sreekant Narumanchi ² , ¹ Princeton Fusion Systems, ² National Renewable Energy Laboratory	
Benefits and Challenges of PCM-based Thermal Management at the Die and Component Level **	67
Meghavin Bhatasana, Amy Marconnet, Purdue University	
Intrachip Cooling Channel Fabrication Using Photo-Electro-Chemical Etching *	
Stephen Schultz, Brigham Young University	

Session 7 - Two Phase Cooling I

Innovative Examination of Composite PCM Capacitor *

Raizner Motti, Rafael – Advanced Defense Systems

A New Edge Micro Data Center and its Passive Thermosyphon Cooling System at TUE:

Cooling System Thermal Performance Tests ** 71

Enzo Minazzo¹, John R. Thome¹, Jackson B. Marcinichen¹, Sean Ahearne², Fred Buining³,
Simon Rommel⁴, Bruno Cimoli⁴, Idelfonso Tafur Monroy⁴, Janos Lazanyi⁵, Mark Fleuren⁶,

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Heat Spreading Using Bubble Pumping in a Thermal Ground Plane *

Hootan Rahimi, University of Texas at Dallas

A Thermal Performance Characterization Method for Thin Vapor Chambers by Photonics Technologies 76

Kuang-Yu Hsu, Wei-Keng Lin, Yi-Jing Chu, Ming-Hsien Hsiao, and Chiao-Jung Tien,
T-Global Technology Co.

Session 8 - Two Phase Cooling II

In Vehicle Validation of a Loop Heat Pipe Used for Cooling an ADAS Compute Module *

Olivier de Laet, Calyos

A Gallium Liquid Metal Phase Change Composite for Transient Thermal Management *

Rachel C. McAfee, DEVCOM US Army Research Laboratory

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As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 41** will begin accepting abstracts during the summer (deadline is October 1, 2024).

We welcome your submissions! Visit us at www.semi-therm.org.

SEMI-THERM 41 is March 10-14, 2025 – *be there!*